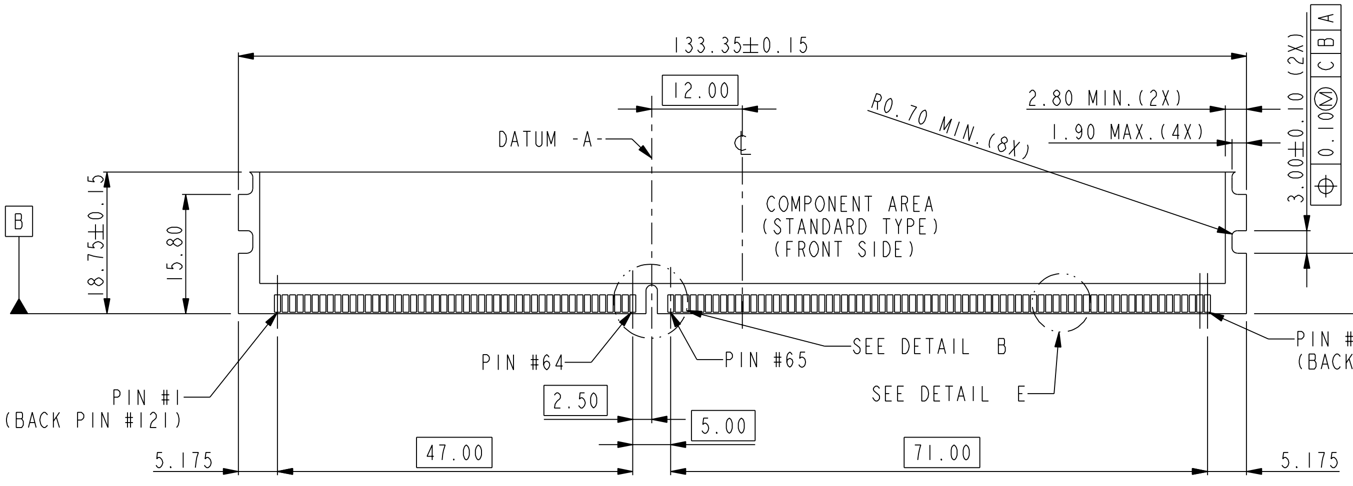
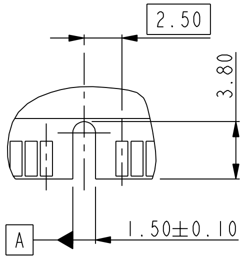
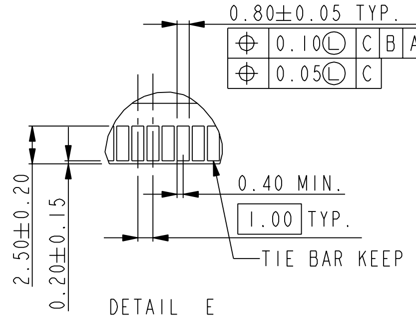


REFERENCE ONLY-SEE MO-269 FOR DETAIL
(VARIATION)DB EB FB GB



DETAIL B
SCALE 2.000



DETAIL E
SCALE 2.000

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DDR3, 240P MEM
catalog no

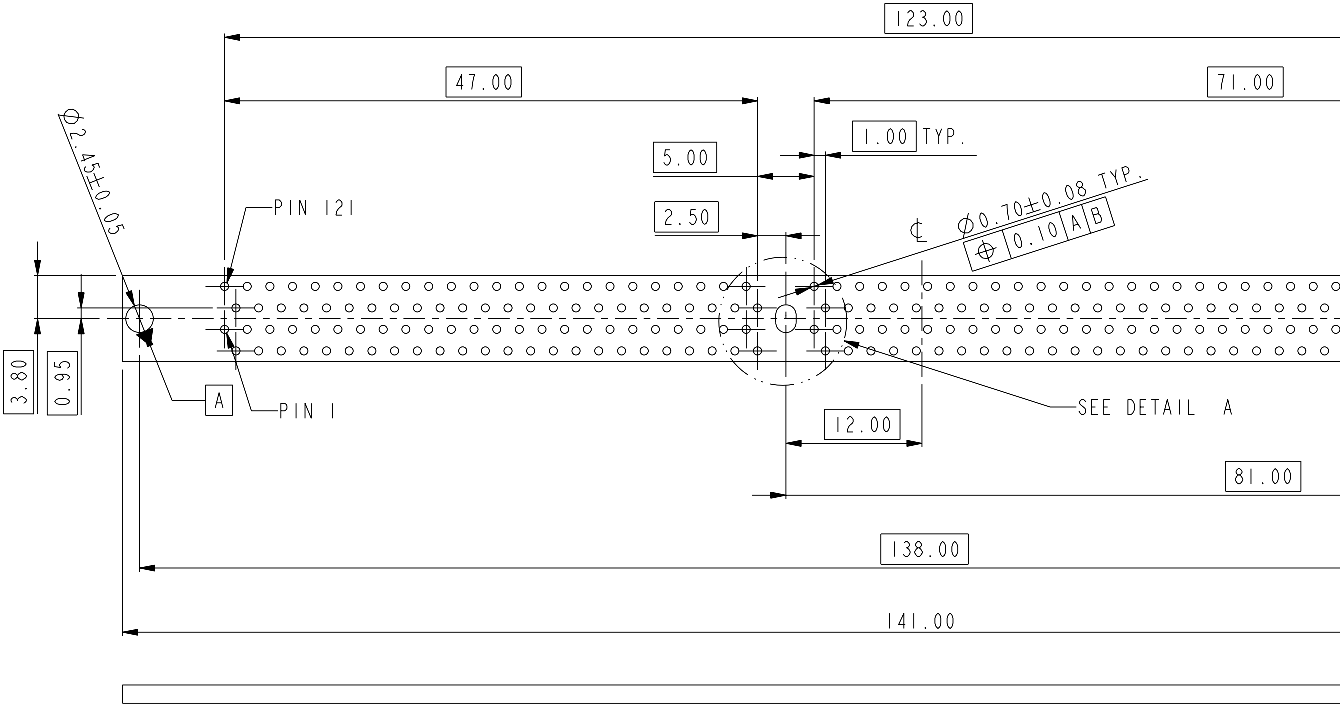
PDM: Rev:D

A

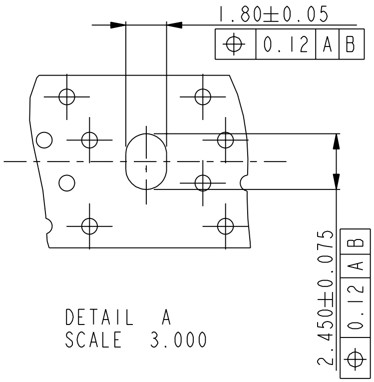
B

C

D



RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



DETAIL A
SCALE 3.000

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catalog no

REV F - 2006-04-17

PDM: Rev:D

10078239 - ☐ ☐ ☐ ☐ ☐

STYLE : MECHANICAL KEYING

1 : 1.5 VOLT. W/ CENTER KEY

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLAT
1LF	10u" (0.25um) MIN. GOLD	100u" (2.54um) MIN. 100% MATTE TIN	50u" (1.27u MIN. NICKEL OVERALL
2LF	15u" (0.38um) MIN. GOLD		
3LF	30u" (0.76um) MIN. GOLD		
4LF	3u" (0.076um) MIN. GOLD		

CONTACT & FORKLOCK LENGTH

CODE	DIM "B"	DIM "D"	PCB THICKNESS
00	2.67 mm	3.50 mm	1.60 MM (0.063")
11	3.18 mm	4.00 mm	2.36 MM (0.093")

COLOR OF HOUSING AND EJECTOR

0 : BLACK HOUSING + IVORY EJECTOR
2 : BLACK HOUSING + BLACK EJECTOR
8 : IVORY HOUSING + IVORY EJECTOR
9 : IVORY HOUSING + BLACK EJECTOR

NOTES:

1. MATERIAL:
   HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
   EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
   TERMINAL: HIGH PERFORMANCE COPPER ALLOY
   METAL CLIP: COPPER ALLOY.

△2 FCI LOGO TO BE APPROXIMATELY LOCATED AS SHOWN ON PRINT.

3. PRODUCT SPECIFICATION: GS-12-368.

4. PACKAGING SPECIFICATION: GS-14-899.

△5 FOR OPTMUM PERFORMANCE. THE TIE BAR IS TO BE ON AN INTERNAL LAYER SO THAT THE REMNANT CANNOT CAUSE CONTACT DAMAGE.

△6 THE DATE CODE IS SHOWN "MM-DD-YY-W". "W" MEANS PRODUCTION LINE.

7. THE REQUIRED PCB THICKNESS IS 1.60MM MINIMUM FOR BOARD LOCK RETENTION.

8. THIS SOCKET MEETS APPLICABLE JEDEC STD.;SOCKET OUTLINE SO-XXX, GAUGE GS-00X AND GS-00X.(SUSPENDED BY JEDEC)

9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

10. THE HOUSING WILL WITH STAND EXPOSURE TO 260 ± 5°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDERING APPLICATION.

11. FROM SEATING PLANE TO TOP MODULE CARD ENGAGEMENT.

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Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

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